

COMPLIANT



GENERAL DESCRIPTION

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitances within ±22% from -55°C to +125°C. This capacitance change is non-linear.

Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency. X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.

TYPICAL ELECTRICAL CHARACTERISTICS





The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.

X7S Dielectric Specifications and Test Methods



Parame	ter/Test	X7S Specification Limits	Measuring Conditions				
Operating Tem	perature Range	-55°C to +125°C	ycle Chamber				
Capacitance Dissipation Factor		Within specified tolerance $\leq 5.0\%$ for $\geq 100V$ DC rating $\leq 5.0\%$ for $\geq 25V$ DC rating $\leq 10.0\%$ for $\geq 10V$ DC rating $\leq 10.0\%$ for $\leq 10V$ DC ratingContact Factory for DF by PN	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 μF, 0.5Vrms @ 120Hz				
Insulation	Resistance	100,000MΩ or 1000MΩ - μF, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity				
Dielectric Strength		No breakdown or visual defects	Charge device with 250% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)				
	Appearance	No defects	Deflection: 2mm Test Time: 30 seconds 1mm/sec				
Resistance to	Capacitance Variation	≤ ±12%					
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)					
	Insulation Resistance	≥ Initial Value x 0.3	90 mm				
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at 230 ± 5°C for 5.0 ± 0.5 seconds				
	Appearance	No defects, <25% leaching of either end terminal					
	Capacitance Variation	≤ ±7.5%					
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.				
	Insulation Resistance	Meets Initial Values (As Above)	5 · · · · · · · · · ·				
	Dielectric Strength	Meets Initial Values (As Above)					
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes			
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes			
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes			
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes			
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure afte 24 ± 2 hours at room temperature				
	Appearance	No visual defects	Charge device with 1.5 rated voltage (≤ 10V) in test chamber set at 125°C ± 2°C				
	Capacitance Variation	≤ ±12.5%					
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou				
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h				
	Dielectric Strength	Meets Initial Values (As Above)					
Load Humidity	Appearance	No visual defects					
	Capacitance Variation	≤ ±12.5%	Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours				
	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with ratec	voltage applied.			
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from chamber and stabilize at r temperature and humidity for				
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours before measuring.				



X7S Dielectric Capacitance Range



PREFERRED SIZES ARE SHADED

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SIZE		0402		0603	0805		1206		1210		
Soldering		Reflow/Wave		Reflow/Wave	Reflow/Wave	Reflow/Wave		ave	Reflow Only		
Packaging		All Paper		All Paper	Paper/Embossed	Pape	Paper/Embossed		Paper/Embossed		
(L) Length mm (in.)		1.00 ± 0.10		1.60 ± 0.15	2.01 ± 0.20		3.20 ± 0.20		3.20 ± 0.20		
		(0.040 ± 0.004)		(0.063 ± 0.006)	(0.079 ± 0.008)	(0.126 ± 0.008)			(0.126 ± 0.008)		
W) Width		0.50 ± 0.10		0.81 ± 0.15	1.25 ± 0.20	1.60 ± 0.20			2.50 ± 0.20		
,	(in.)	(0.020 ± 0.004)		(0.032 ± 0.006)	(0.049 ± 0.008)	(0.063 ± 0.008)			(0.098 ± 0.008)		
(t)	mm		0.25 ± 0.15 0.35 ± 0.15 0.50 ± 0.25		0.50 ± 0.25			0.50 ± 0.25			
Terminal	(in.)	(0.010 ± 0.006)		(0.014 ± 0.006)	(0.020 ± 0.010)	(0.020 ± 0.010)			(0.020 ± 0.010)		
	WVDC	4	6.3	6.3	4	10	50	100	6.3		
Сар	100										
(pF)	150										
	220					ļ	' _		<u> </u>		
	330							\sim	-W-		
	470					\checkmark	~				
	680						$(\)$	7	レ		
	1000						5				
	1500										
	2200					1		t			
	3300										
	4700										
	6800										
Сар	0.010										
(µF)	0.015										
	0.022										
	0.033		С								
	0.047		С								
	0.068		С								
	0.10		C				1				
	0.15			1							
	0.22										
	0.33			G		1	1	1			
	0.47			G							
	0.68			G							
	1.0	E		G							
	1.5				N	1					
	2.2	E			N						
	3.3				N		1	1			
	4.7				N	Q					
	10						1				
	22								Z		
	47										
	100										
	WVDC	4	6.3	6.3	4	10	50	100	6.3		
	SIZE 0402		0603	0805	1	1206		1210			

Letter	A	С	E	G	J	K	М	N	Р	Q	Х	Y	Z
Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.90	2.29	2.54	2.79
Thickne	ss (0.01	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.075)	(0.090)	(0.100)	(0.110)
		PAPER					EMBOSSED						

*Contact Factory for Specifications



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